

Fig. 1

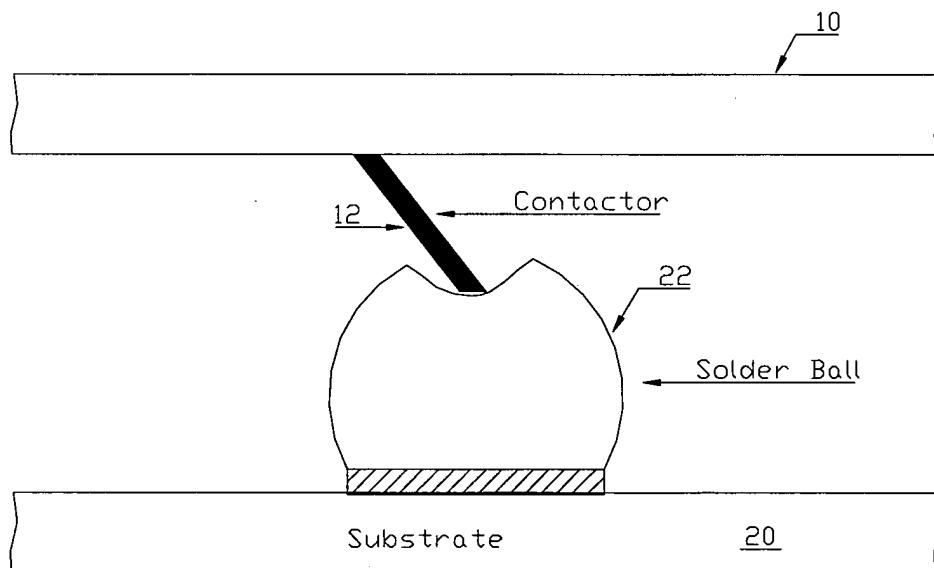


Fig. 2A

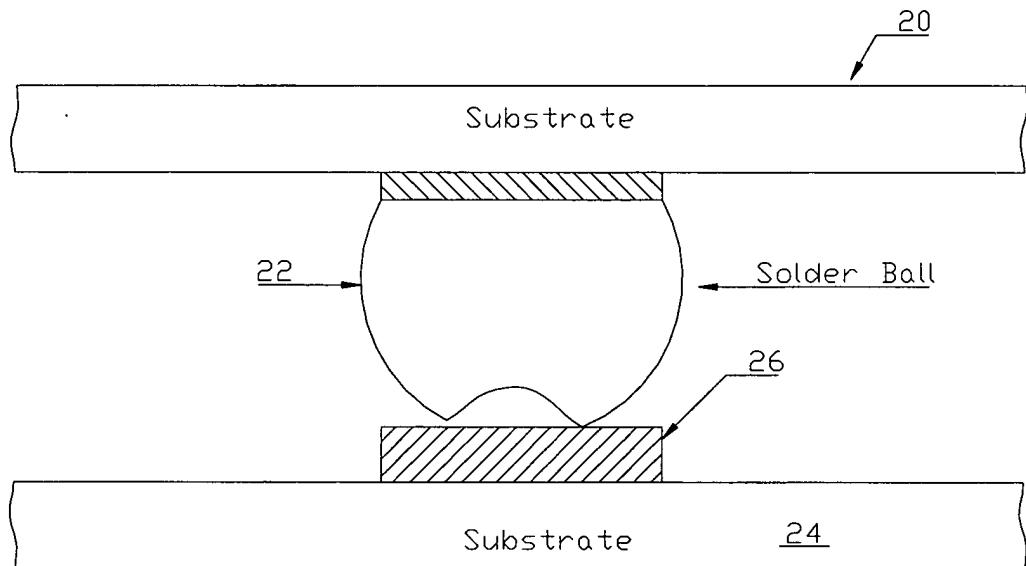


Fig. 2B

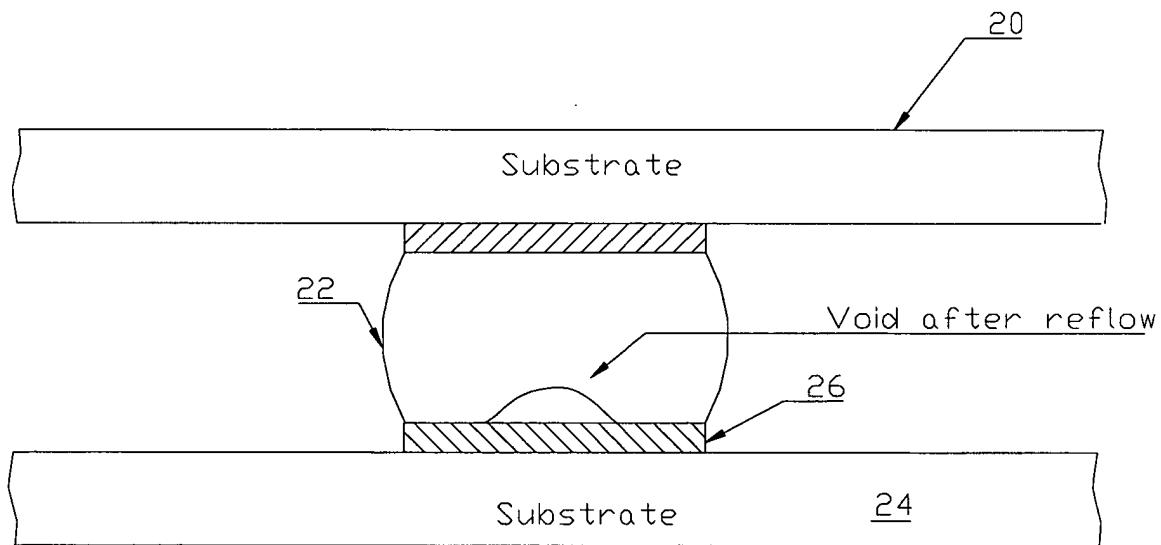


Fig. 2C

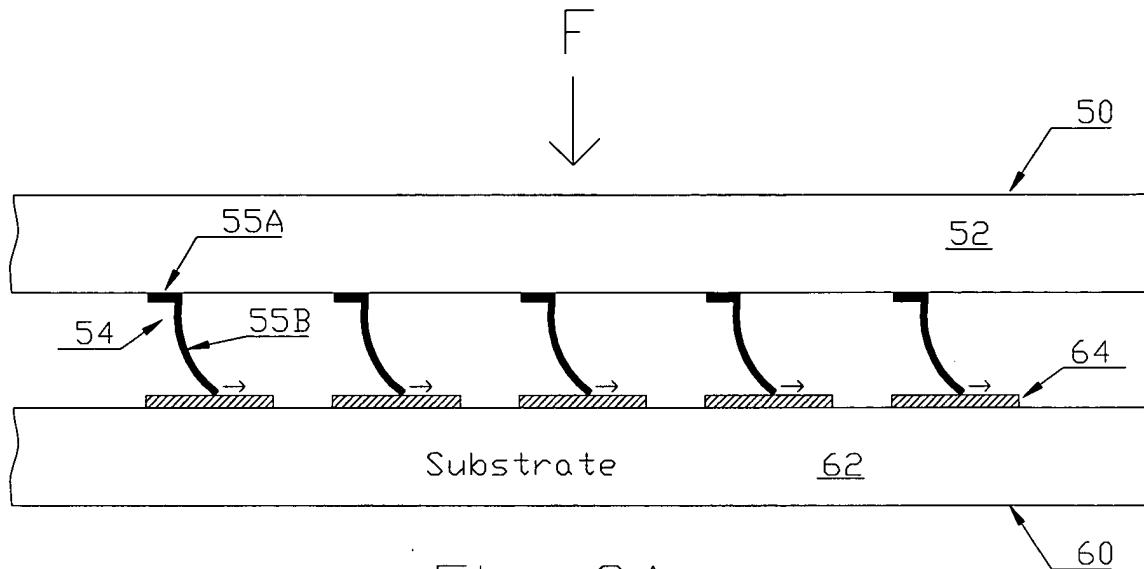


Fig. 3A

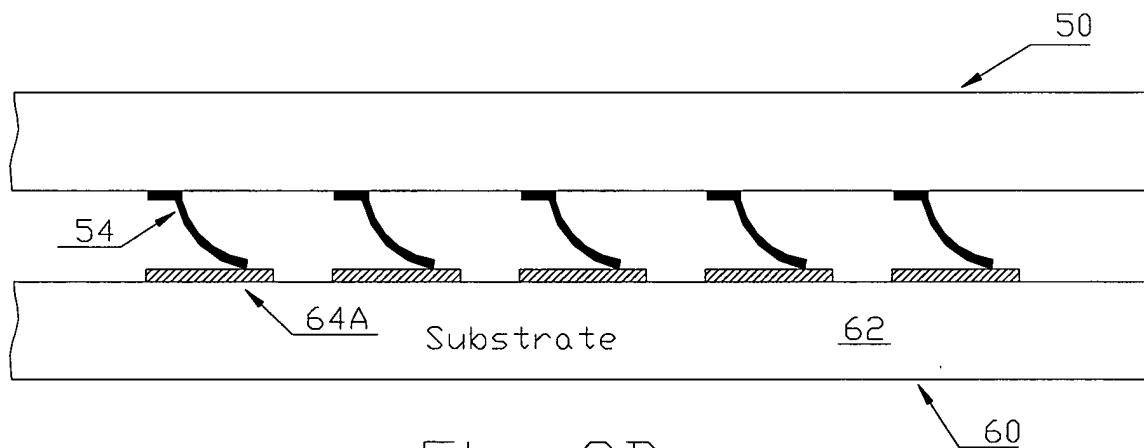


Fig. 3B

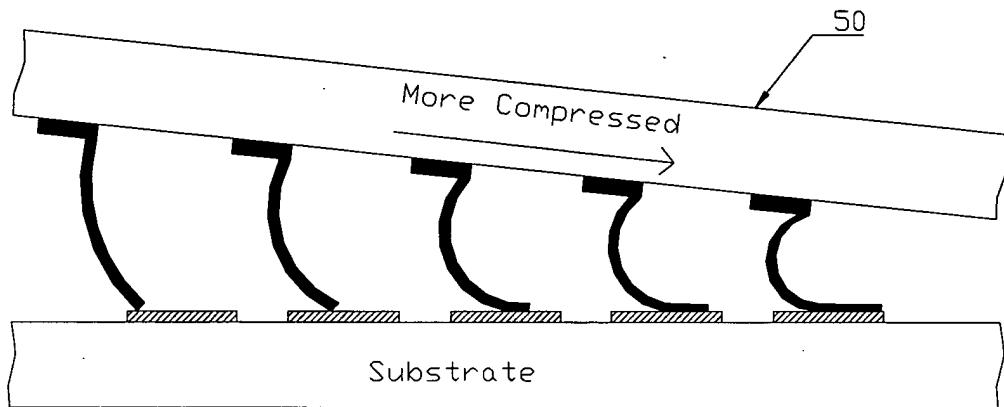


Fig. 4A

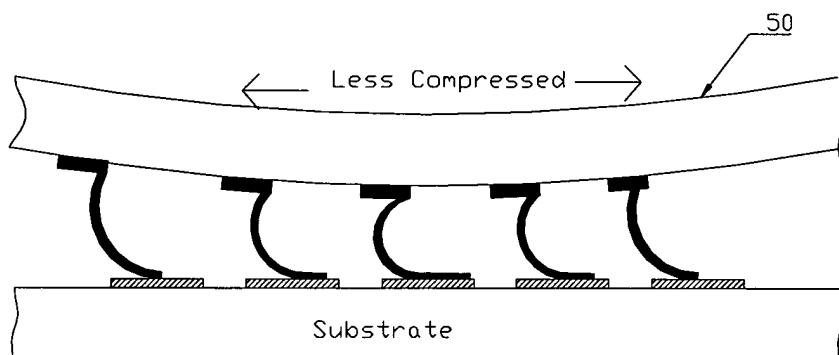
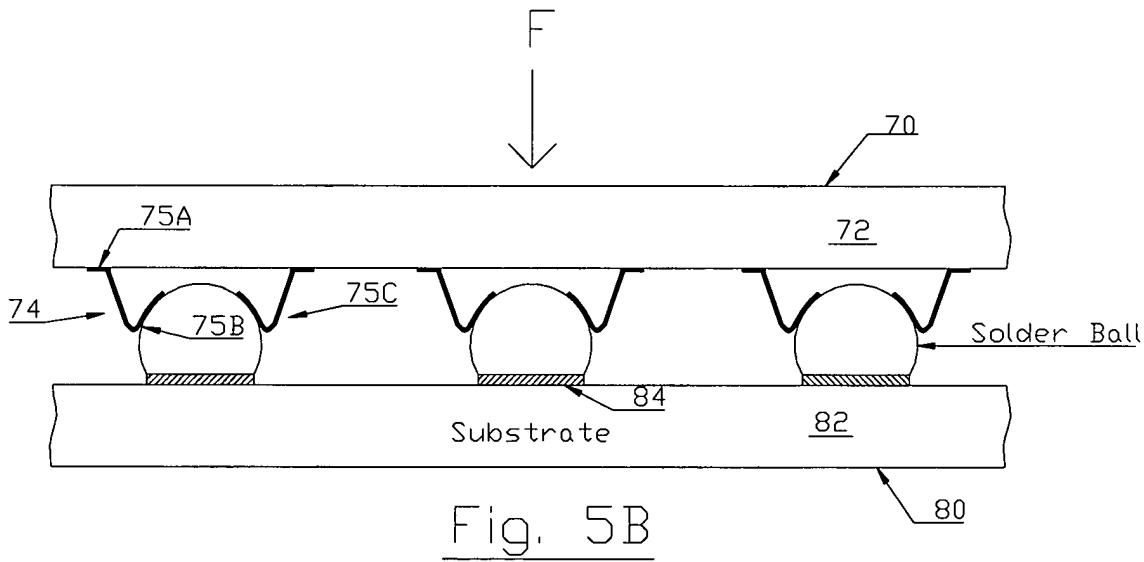
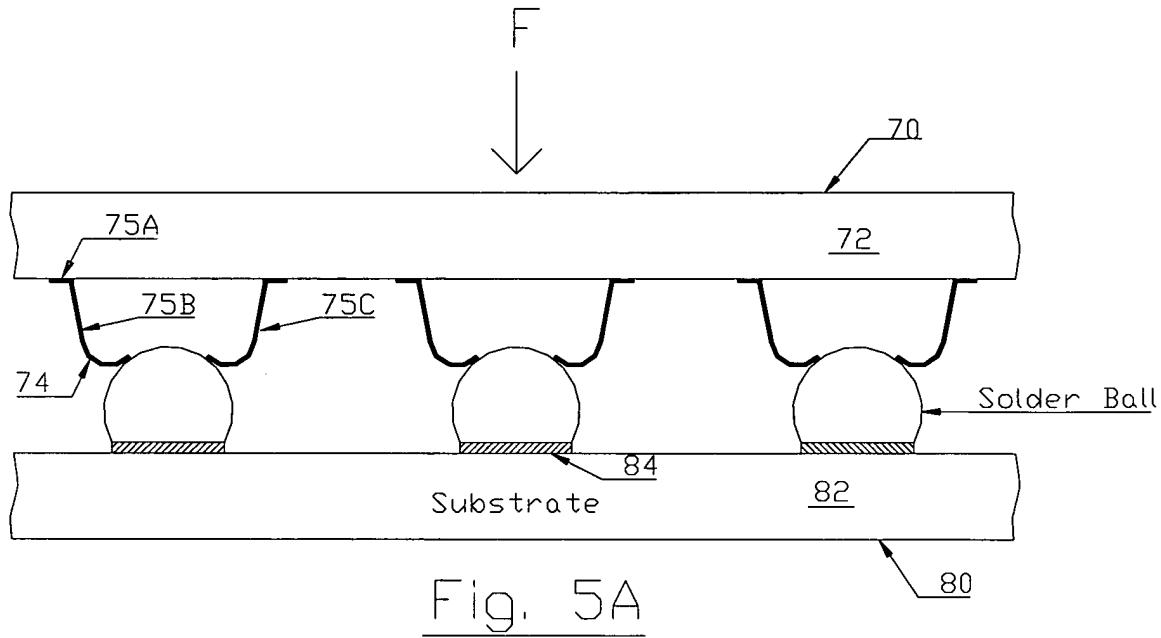
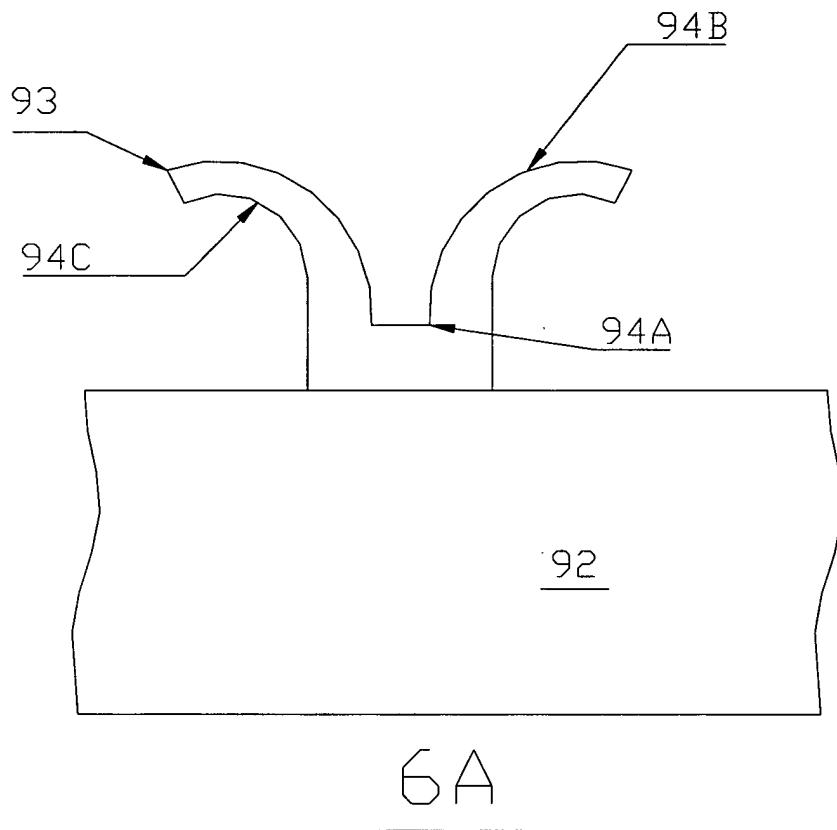


Fig. 4B





6A

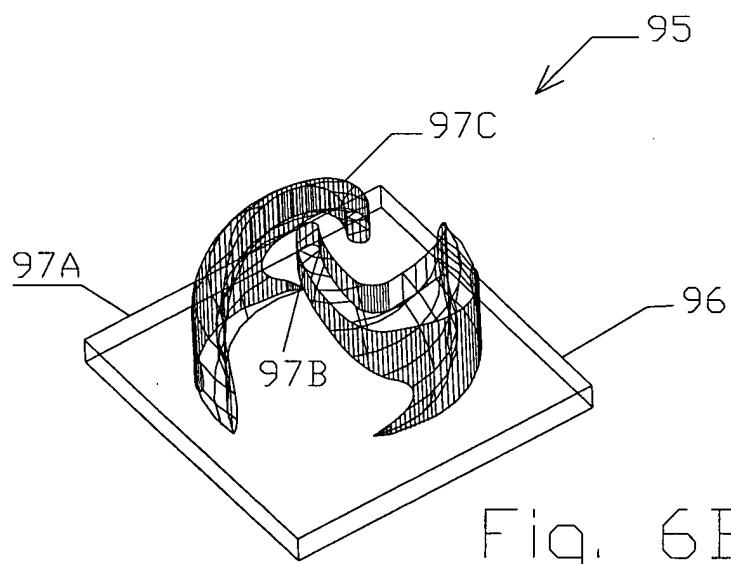


Fig. 6B

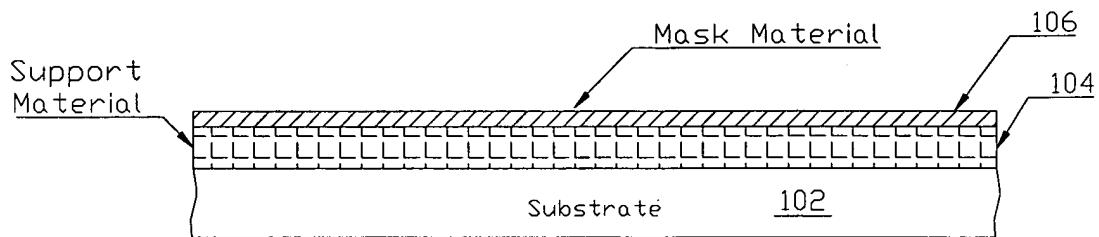


Fig. 7A

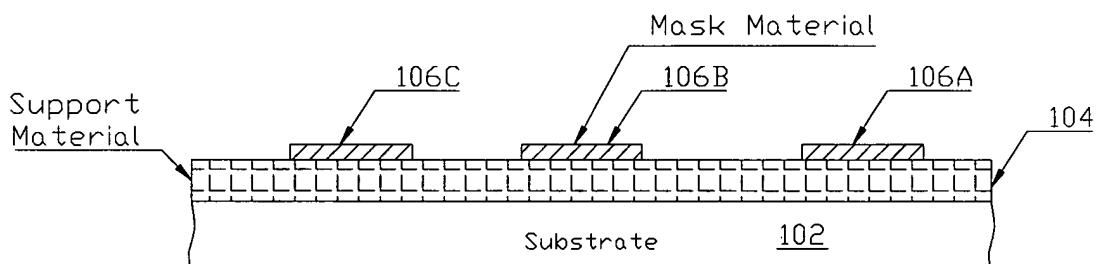


Fig. 7B

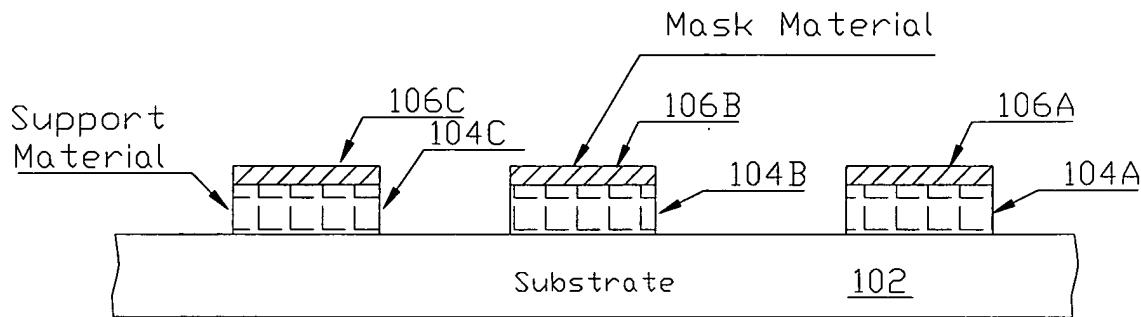


Fig. 7C

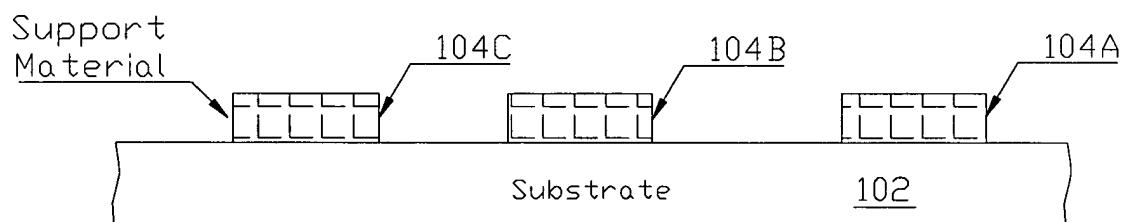


Fig. 7D

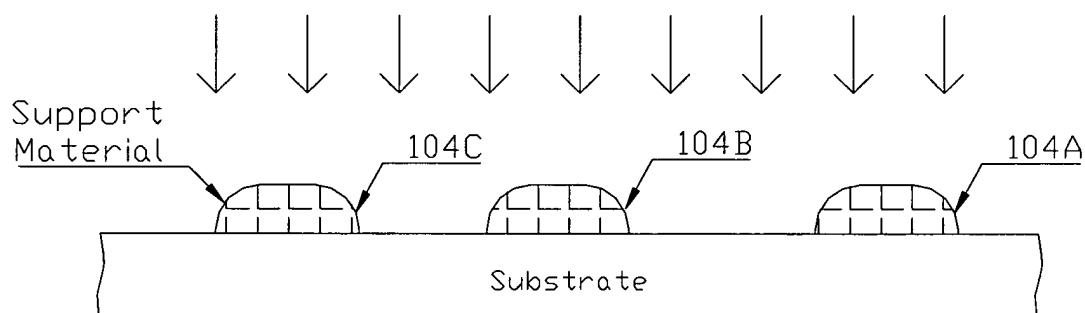


Fig. 7E

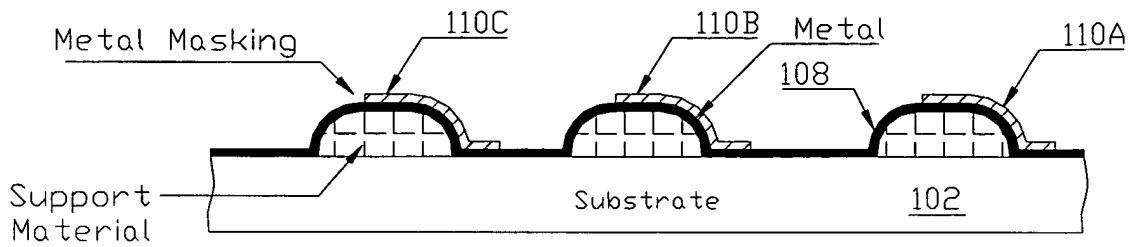


Fig. 7F

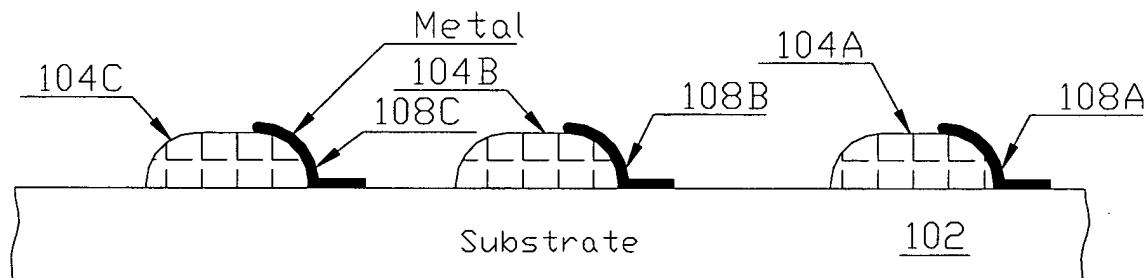


Fig. 7G

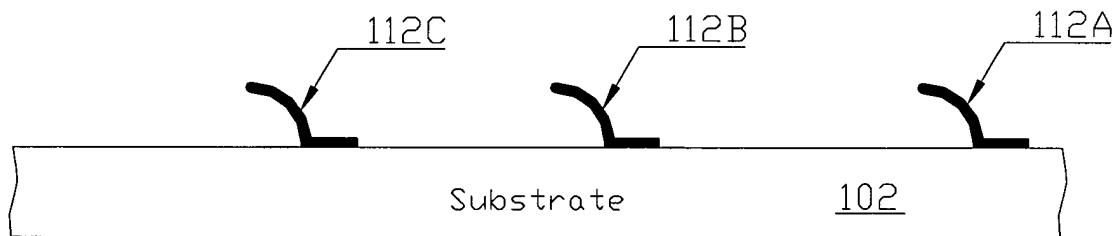


Fig. 7H

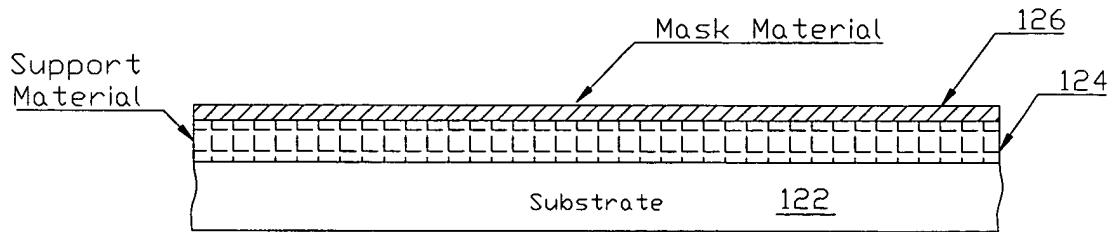


Fig. 8A

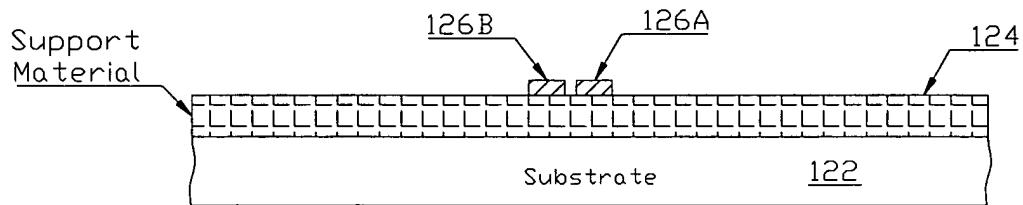


Fig. 8B

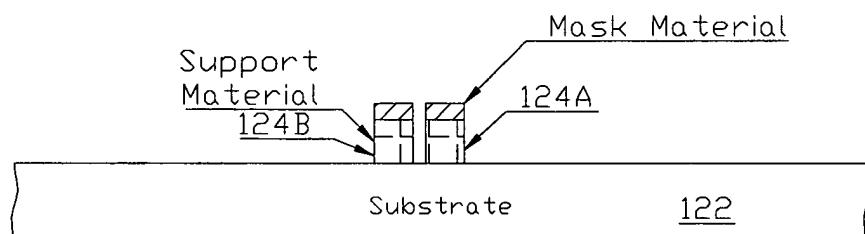


Fig. 8C

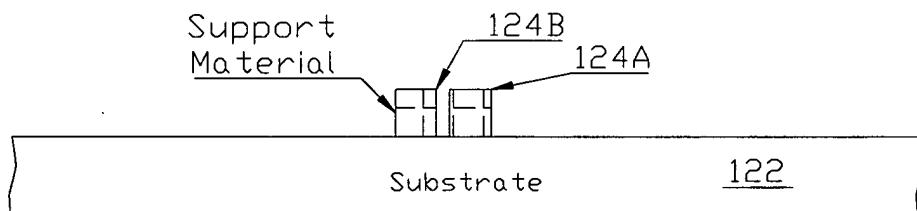


Fig. 8D

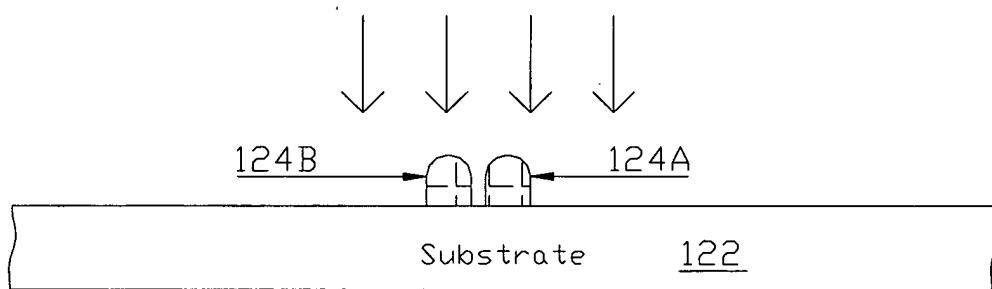


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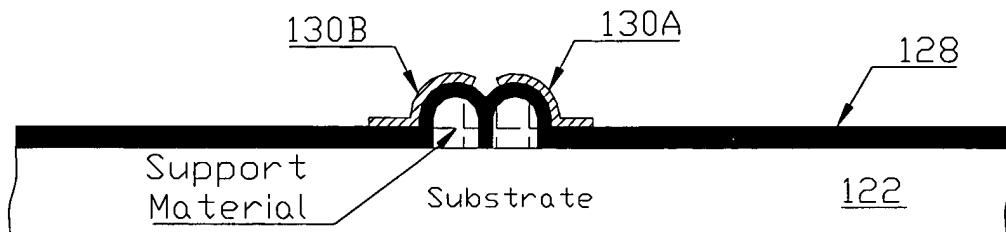


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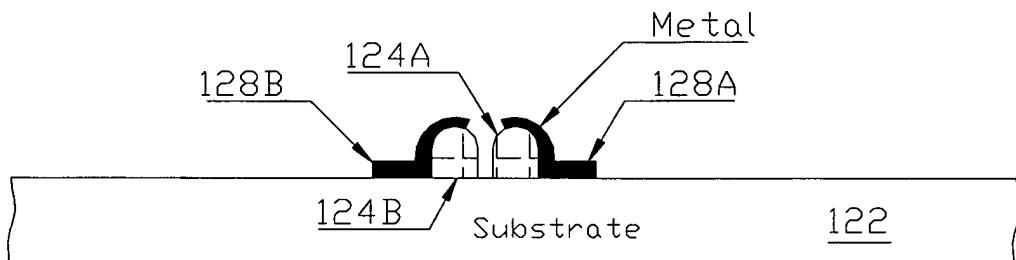


Fig. 8G

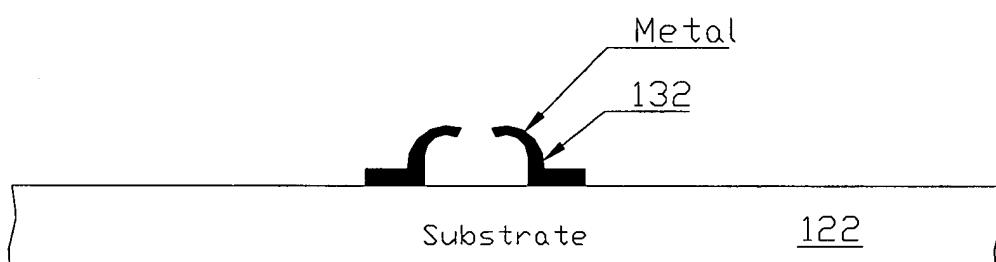


Fig. 8H

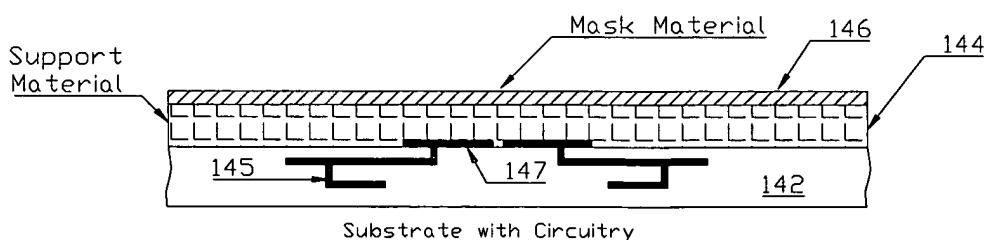


Fig. 9A

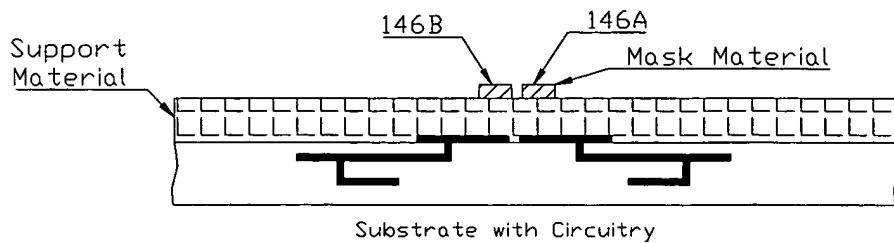


Fig. 9B

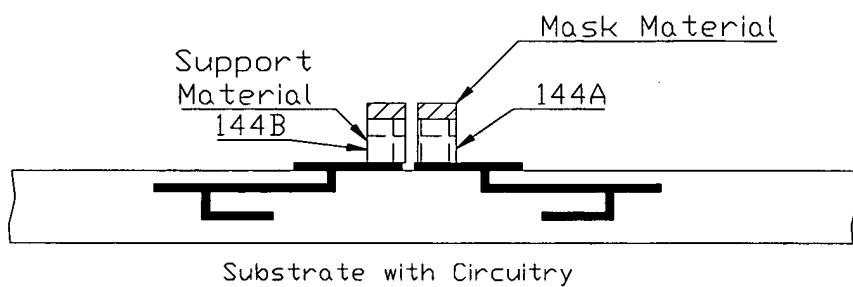


Fig. 9C

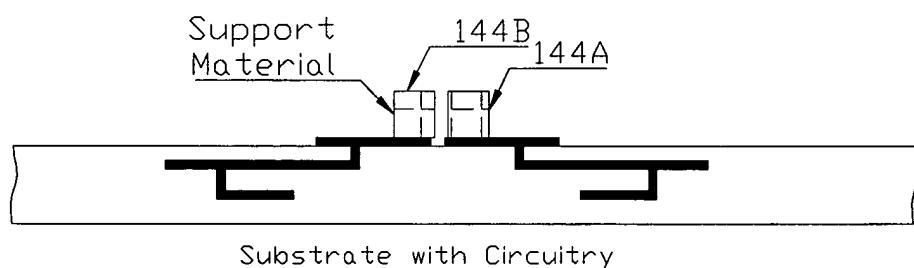


Fig. 9D

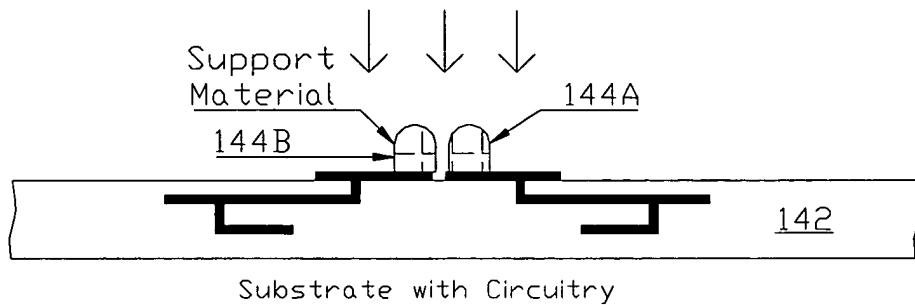


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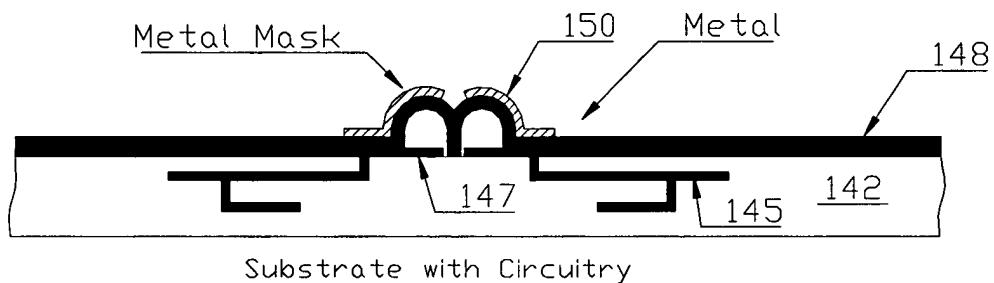


Fig. 9F

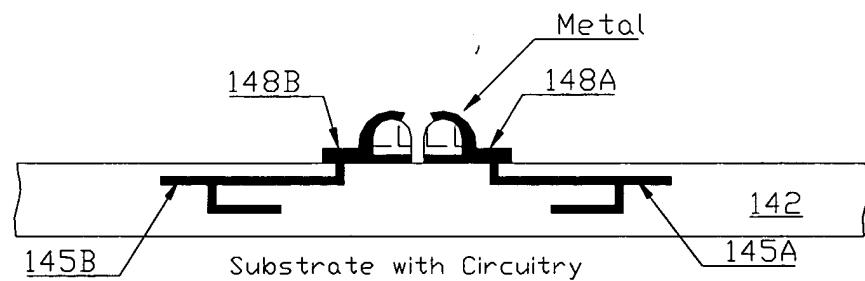
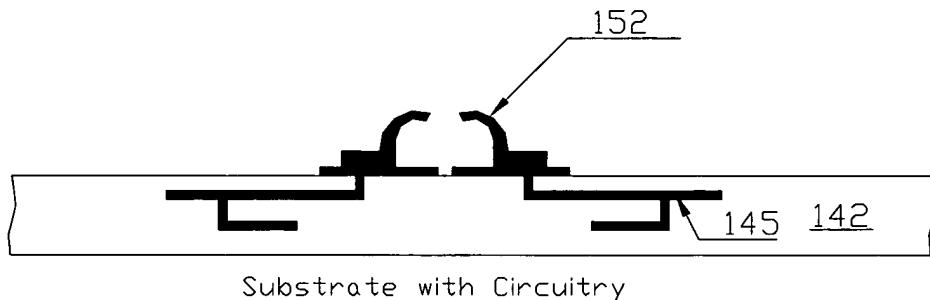


Fig. 9G



Substrate with Circuitry

Fig. 9H

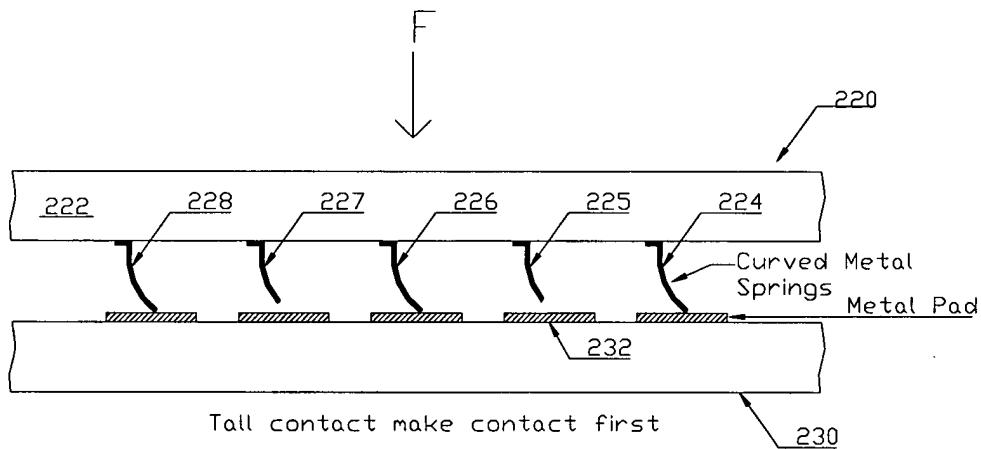
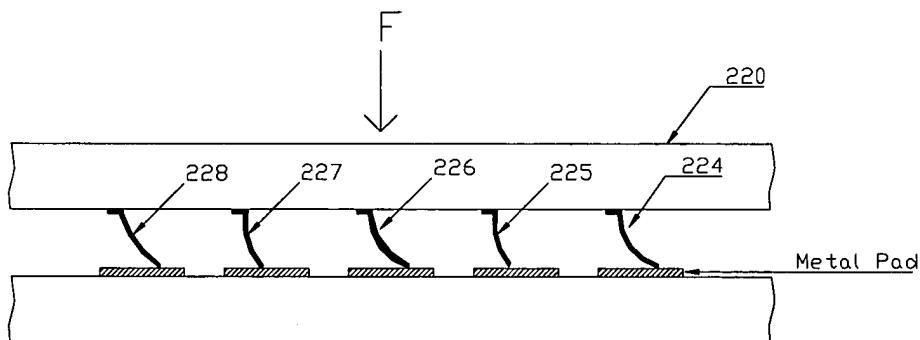


Fig. 10A



Increasing compression, leads to all contacts making connection

Fig. 10B

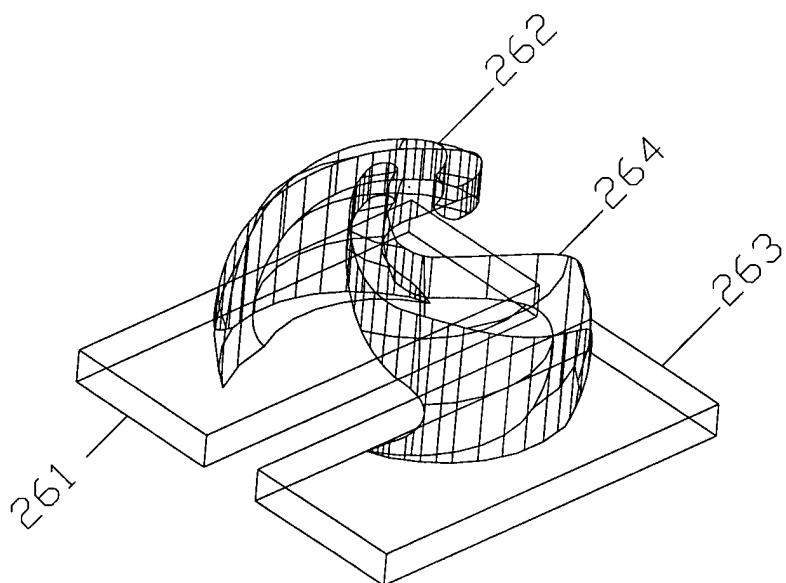
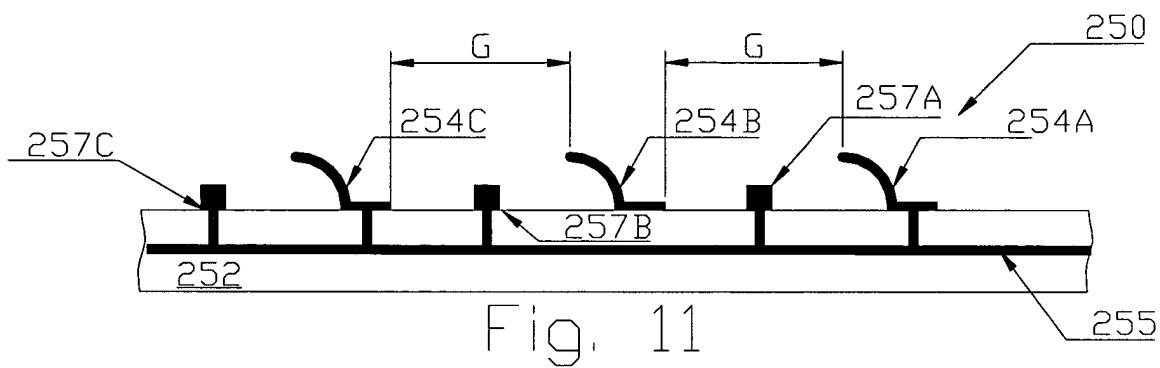


Fig. 12

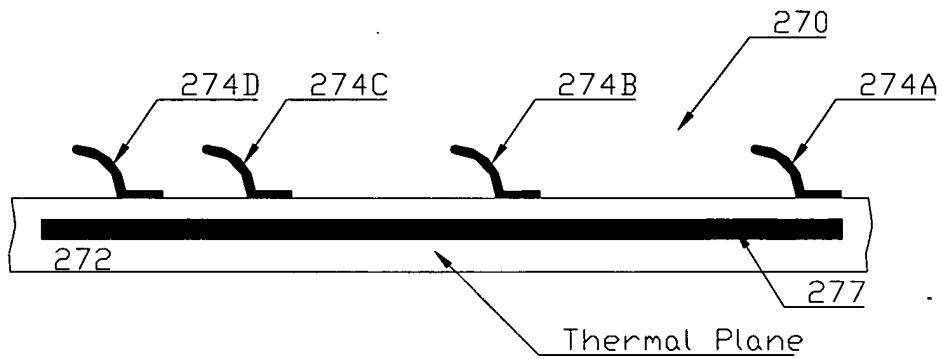


Fig. 13

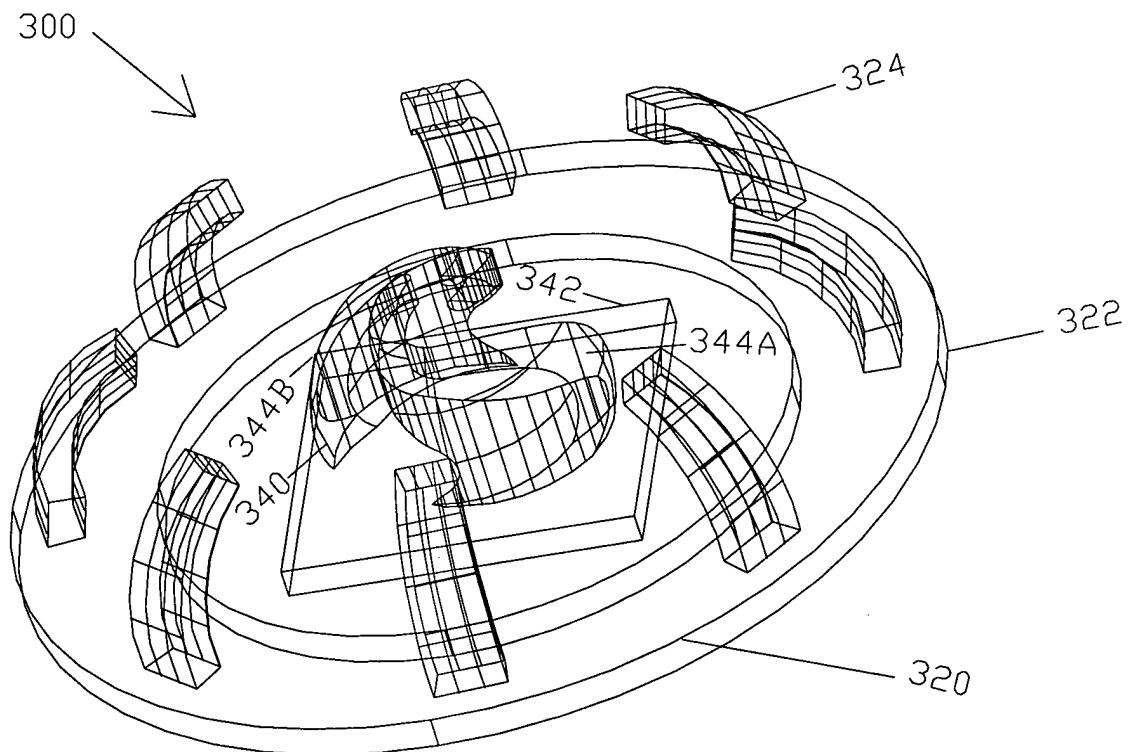


Fig. 14

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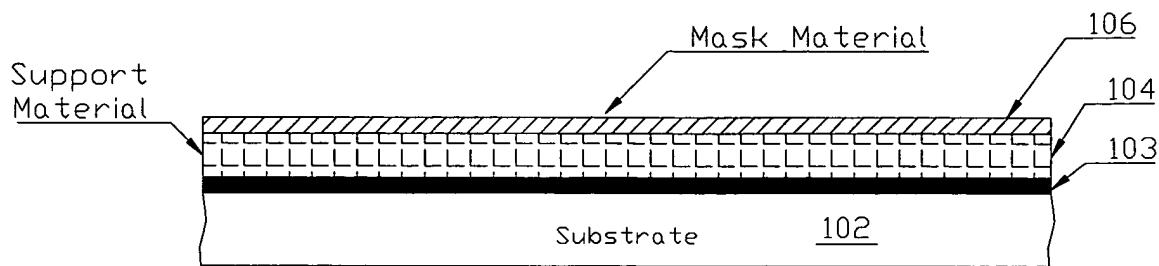


Fig. 15A

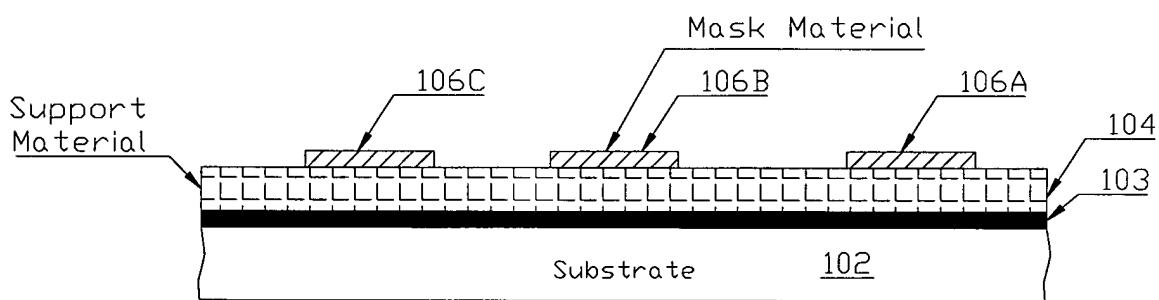


Fig. 15B

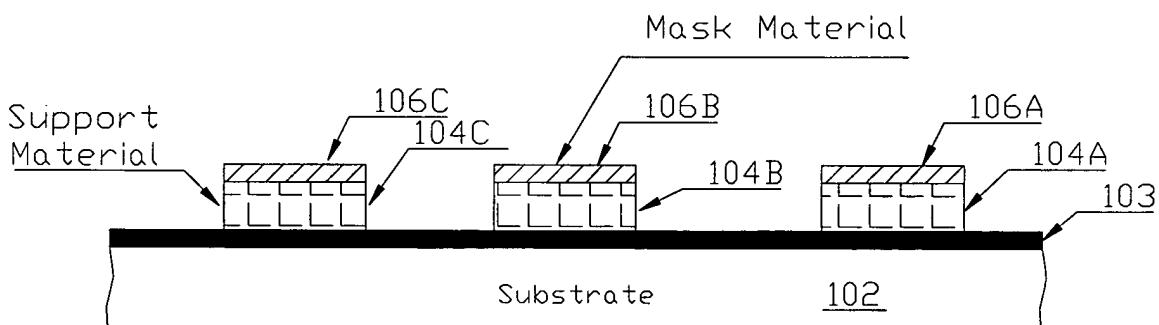


Fig. 15C

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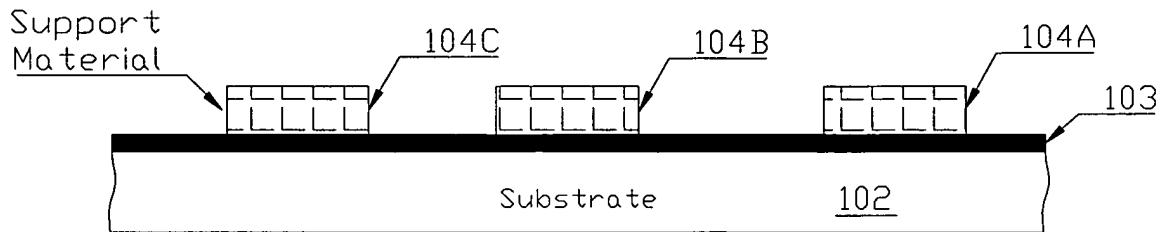


Fig. 15D

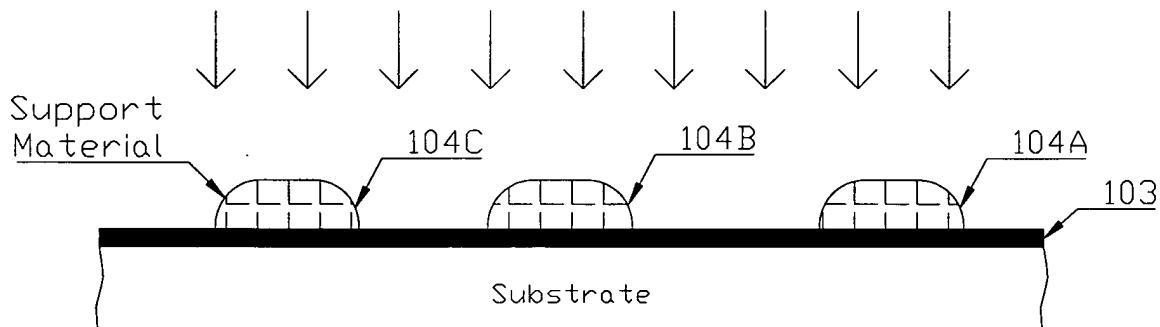


Fig. 15E

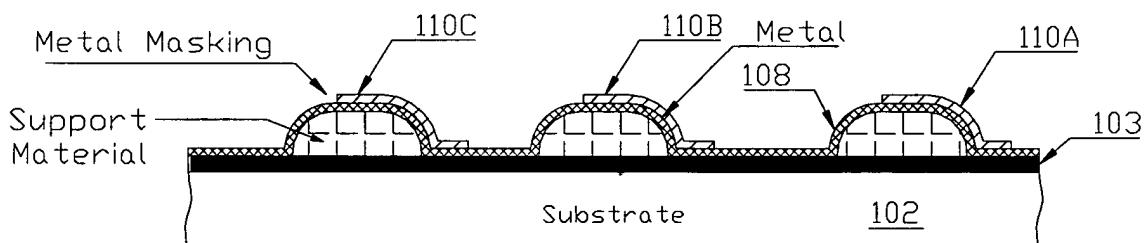


Fig. 15F

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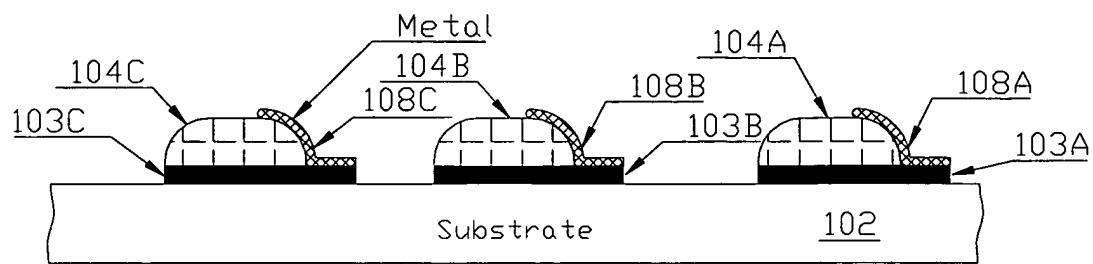


Fig. 15G

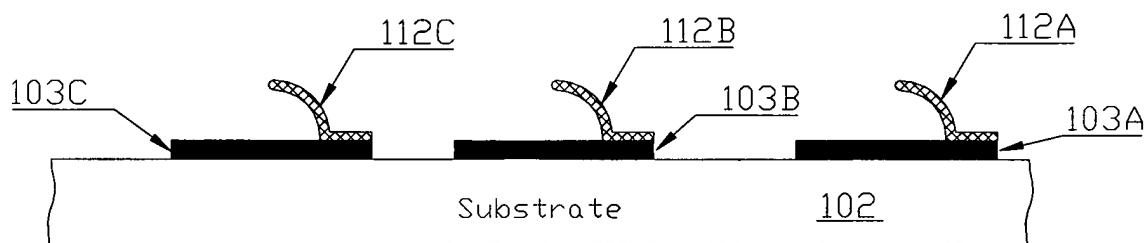


Fig. 15H

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